

# Special issue on advanced fabrication technologies and applications of flexible and deformable devices

## Call for Papers

Flexibility and deformability are attractive features in soft electronics, enabling the development of wearable and implantable devices that are comfortable, non-invasive, and compatible with human activities. Flexible devices have emerged as powerful tools for studying human biology, fitness, and wellness applications. The last decade has experienced rapid growth and tremendous progress in microfabrication technologies and miniaturization processes for soft electronics. This special issue will review the frontier research on flexible devices, as well as the advanced technologies and smart concepts behind them.

The scope of this issue will cover but not be limited to the following topics:

- Novel fabrication technologies and smart designs
- Material developments
- Wireless technologies for soft electronics
- Device fabrication and evaluation
- Applications of flexible and deformable microdevices
- Peripheral control circuits and user interfaces for humanoid applications
- Demonstration of wearable and flexible devices on animal models or humans

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